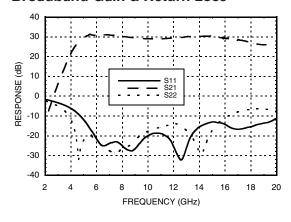


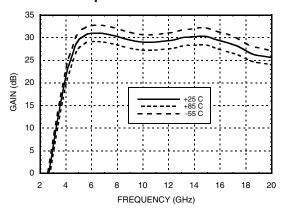


GaAs PHEMT MMIC DRIVER AMPLIFIER, 5.5 - 17 GHz

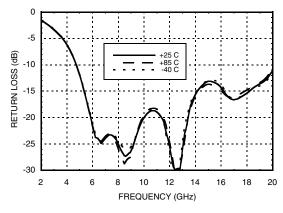
Broadband Gain & Return Loss



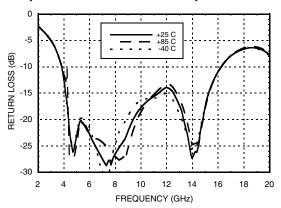
Gain vs. Temperature



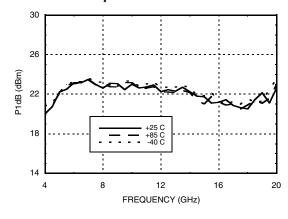
Input Return Loss vs. Temperature



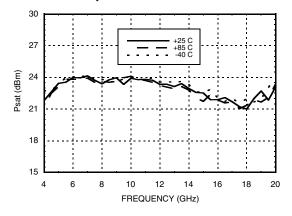
Output Return Loss vs. Temperature



P1dB vs. Temperature



Psat vs. Temperature

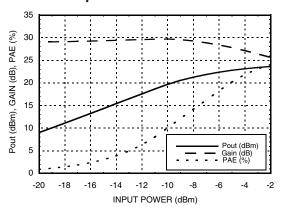




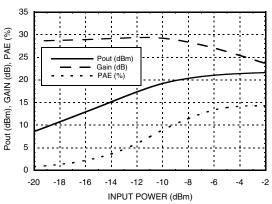


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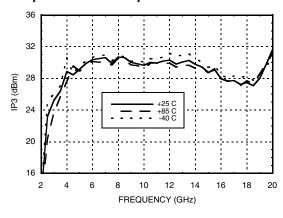
Power Compression @ 11 GHz



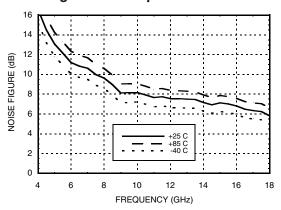
Power Compression @ 17 GHz



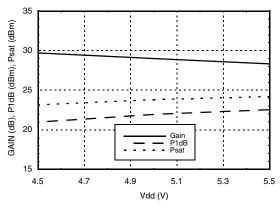
Output IP3 vs. Temperature



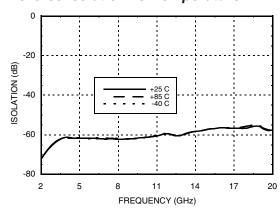
Noise Figure vs. Temperature



Gain & Power vs. Supply Voltage @ 11 GHz



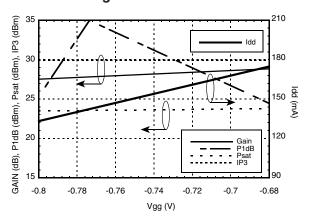
Reverse Isolation vs. Temperature







Gain, Power & Output IP3 vs. Gate Voltage @ 11 GHz



Typical Supply Current vs. Vdd

Vdd (V)	Idd (mA)
4.5	177
5.0	180
5.5	182

Note: Amplifier will operate over full voltage ranges shown above

GaAs PHEMT MMIC DRIVER AMPLIFIER, 5.5 - 17 GHz

Absolute Maximum Ratings

Drain Bias Voltage (Vdd1, Vdd2, Vdd3, Vdd4)	+5.5V
Gate Bias Voltage (Vgg)	-3 to 0V
RF Input Power (RFIN)(Vdd = +5 Vdc)	+5 dBm
Channel Temperature	175 °C
Continuous Pdiss (T= 85 °C) (derate 11.08 mW/°C above 85 °C)	0.99 W
Thermal Resistance (channel to package bottom)	90.23 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

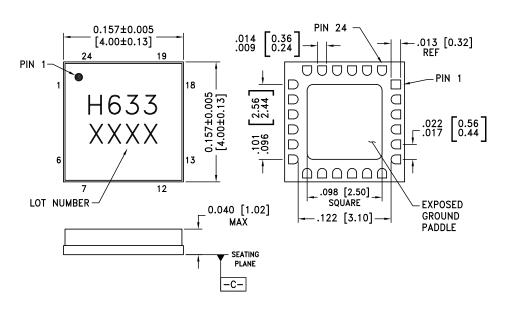




GaAs PHEMT MMIC DRIVER AMPLIFIER, 5.5 - 17 GHz

Outline Drawing

BOTTOM VIEW



NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING: 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM -C-
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC633LC4	Alumina, White	Gold over Nickel	MSL3 [1]	H633 XXXX

^[1] Max peak reflow temperature of 260 °C

^{[2] 4-}Digit lot number XXXX





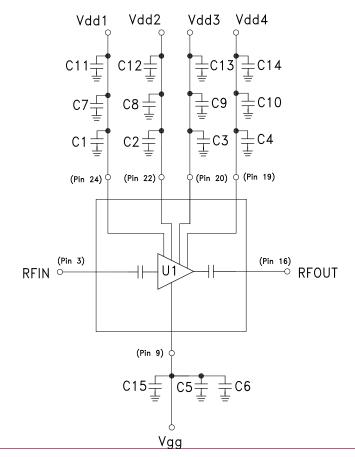
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Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 5 - 8, 11 - 14, 18, 21, 23	N/C	No connection. These pins may be connected to DC/RF ground. Performance will not be affected.	
2, 4, 15, 17	GND	Package Bottom must be connected to RF/DC ground.	
3	RFIN	This pin is AC coupled and matched to 50 Ohms.	RFIN O———
9	Vgg	Gate control for amplifier, please follow "MMIC Amplifier Biasing Procedure" Application Note: See application circuit for required external components.	Vgg O
16	RFOUT	This pin is AC coupled and matched to 50 Ohms.	— —○ RFOUT
24, 22, 20, 19	Vdd1, Vdd2, Vdd3, Vdd4	Power Supply Voltage for the amplifier. See application circuit for required external components.	Vdd1,2,3,4

Application Circuit

Component	Value
C1 - C5	100 pF
C6 - C10	1000 pF
C11 - C15	2.2 µF



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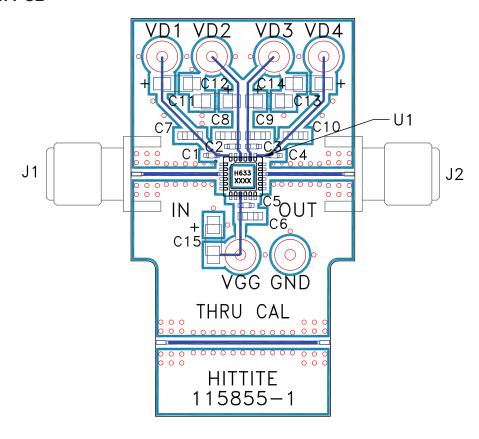
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Evaluation PCB



List of Materials for Evaluation PCB 115857 [1]

Item	Description
J1 - J2	2.92 mm PC Mount K-Connector
VD1 - VD4	DC Pin
C1 - C5	100 pF Capacitor, 0402 Pkg.
C6 - C10	1000 pF Capacitor, 0603 Pkg.
C11 - C15	2.2 μF Capacitor, Tantalum
U1	HMC633LC4 Driver Amplifier
PCB [2]	115855 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.







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